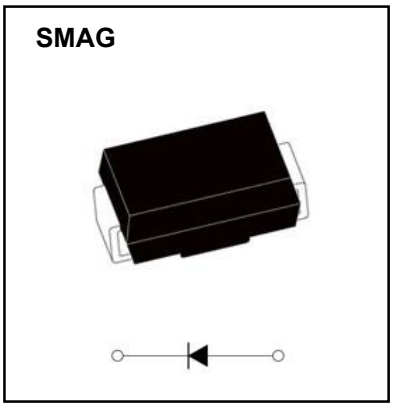
SZCJ

Shenzhen Changji Semiconductor Co., LTD.

Features

- $I_{F(AV)}$ 5A
- V_{RRM} 20V-200V
- High surge current capability
- Polarity: Color band denotes cathode



Applications

- Rectifier

Marking

- SS5X

  X：From 2 To 20

Li lues(Absolute Maximum Rating)

m	Symbol	Unit	Test Conditions	SS5								
				2	3	4	5	6	8	10	15	20
Repetitive Peak Reverse Voltage	V_{RRM}	V		20	30	40	50	60	80	100	150	200
Maximum RMS Voltage	V_{RMS}	V		14	21	28	35	42	56	70	105	140
Average Forward Current	$I_{F(AV)}$	A	60Hz Half-sine wave, Resistance load	5.0								
Surge(Non-repetitive)Forward Current	I_{FSM}	A	60Hz Half-sine wave, 1 cycle, Ta=25℃	150								
Junction Temperature	T_J	℃		-55 ~ +150								
Storage Temperature	T_{STG}	℃		-55 ~ +150								

Electrical Characteristics (T =25℃ Unless otherwise specified)

Item	Symbol	Unit	Test Condition		SS5								
					2	3	4	5	6	8	10	15	20
Peak Forward Voltage	V_F	V	I_F=5.0A		0.55			0.70		0.85		0.95	
Peak Reverse Current	I_{RRM1}	mA	$V_{RM}=V_{RRM}$	T_a=25℃	0.5					0.1			
	I_{RRM2}			T_a=100℃	10					5			
Thermal Resistance(Typical)	$R_{\theta J-C}$	℃/W	Between junction and case		7.0								
	$R_{\theta J-A}$		Between junction and ambient		52.5								
	$R_{\theta J-L}$		Between junction and terminal		16								
Juction Capacitance (Typical)	Cj	pF	Measured at 1MHZ and Applied Reverse Voltage of 4.0 V.D.C		260			220		130		100	80
Reverse recovery time(Typical)	t_{rr}	ns	I_F= 0.5A, I_R=1A,I_{rr}=0.25A		20			16		5		5	10

Typical Characteristics

FIG.1:FORWARD CURRENT DERATING CURVE

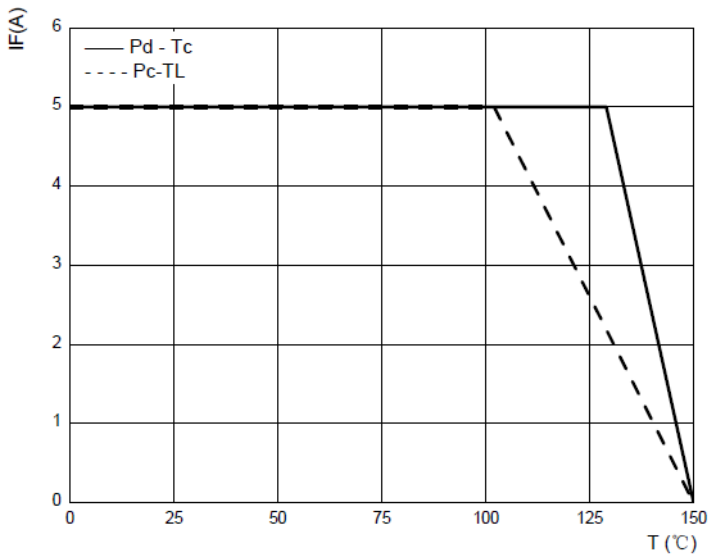
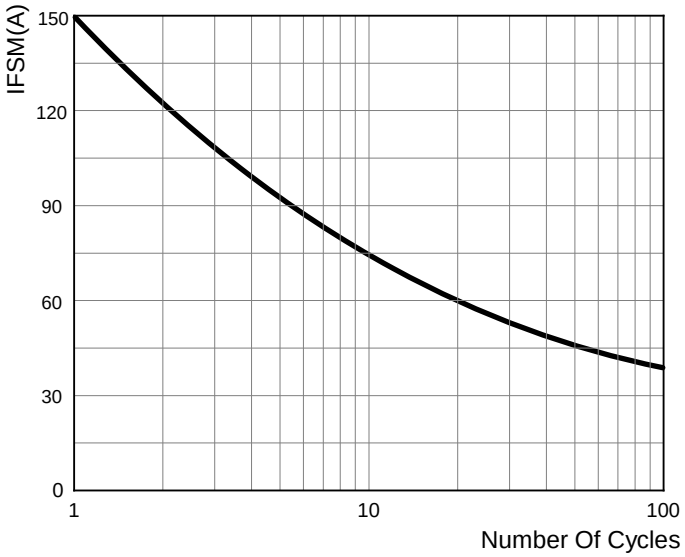
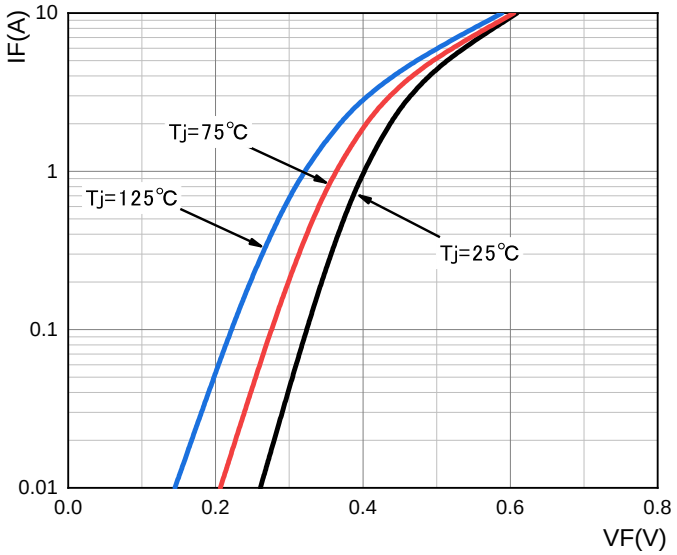


FIG 2: MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT



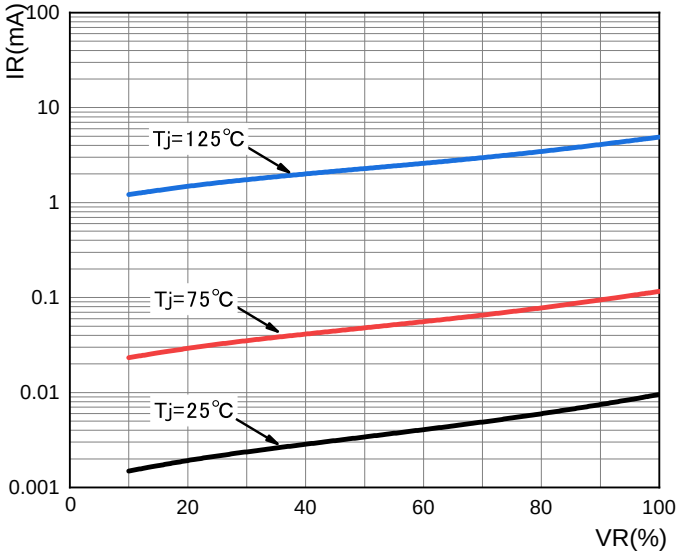
SS52-SS54

FIG.3: TYPICAL FORWARD CHARACTERISTICS



SS52-SS54

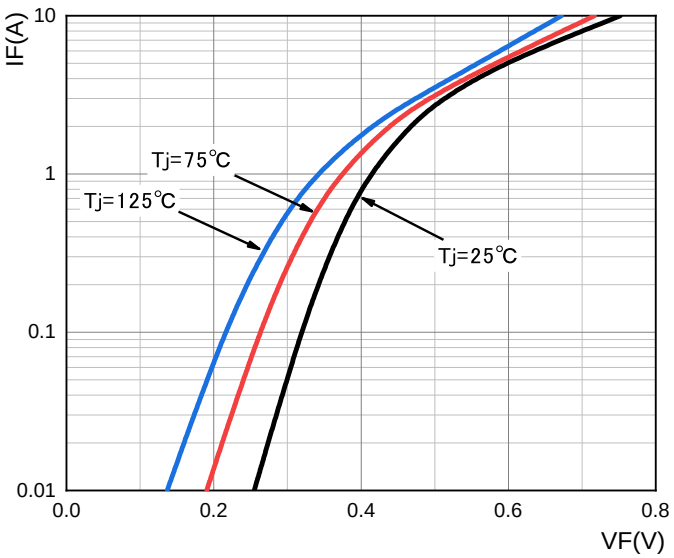
FIG.4: TYPICAL REVERSE CHARACTERISTICS



Typical Characteristics

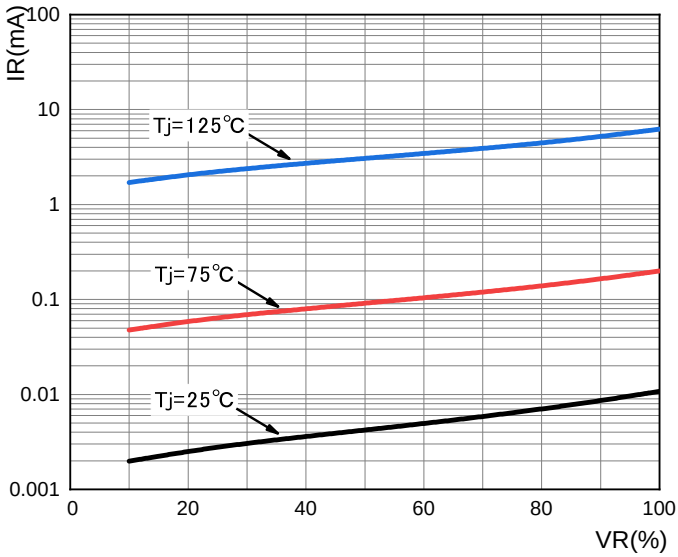
SS55-SS56

FIG.5: TYPICAL FORWARD CHARACTERISTICS



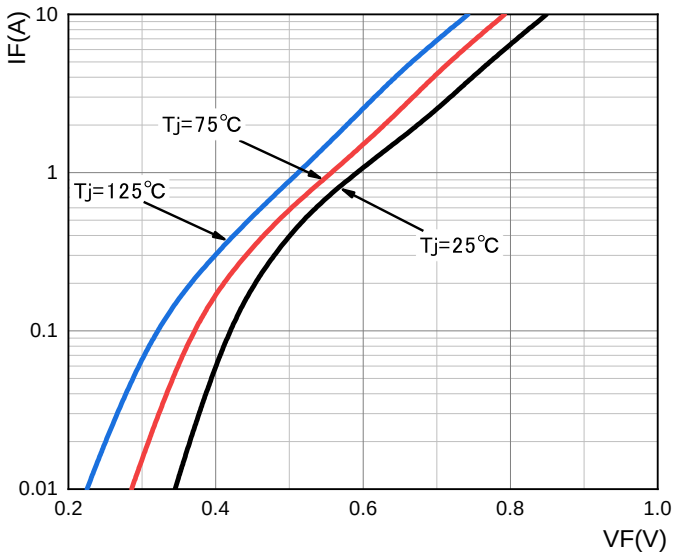
SS55-SS56

FIG.6: TYPICAL REVERSE CHARACTERISTICS



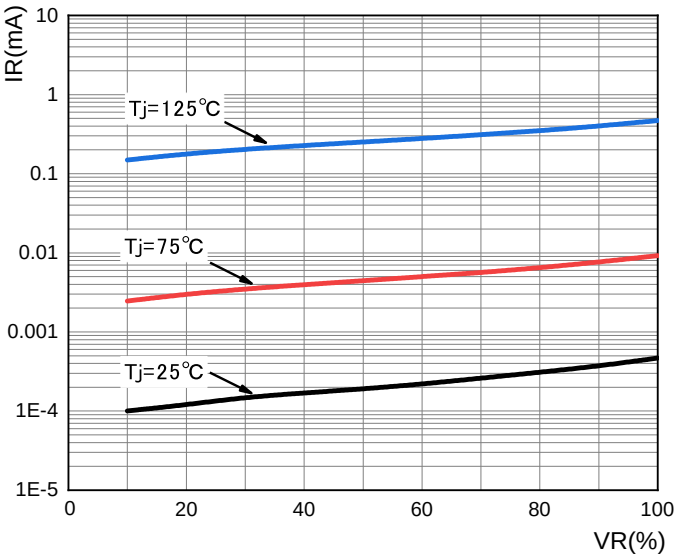
SS58-SS510

FIG.7: TYPICAL FORWARD CHARACTERISTICS



SS58-SS510

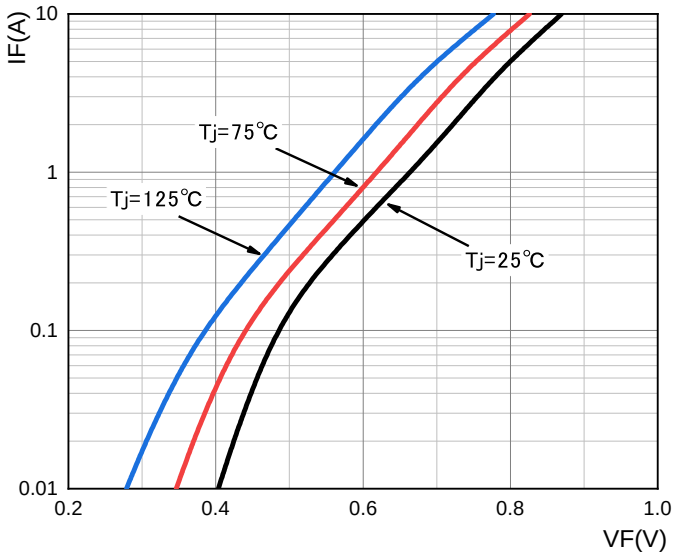
FIG.8: TYPICAL REVERSE CHARACTERISTICS



Typical Characteristics

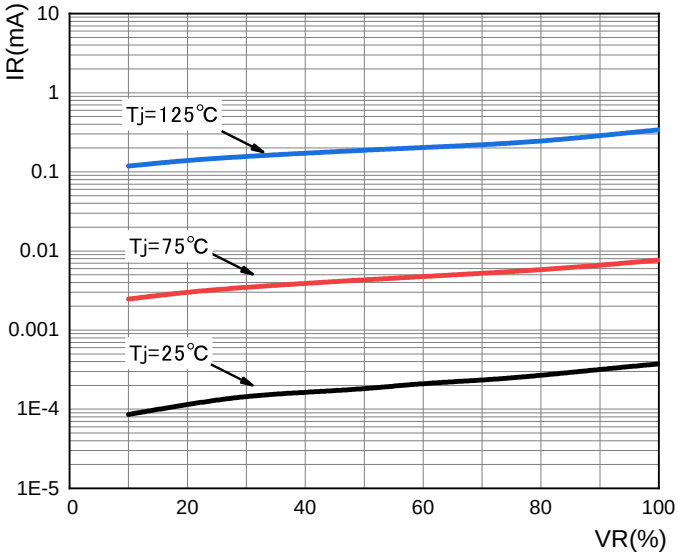
SS515

FIG.9: TYPICAL FORWARD CHARACTERISTICS



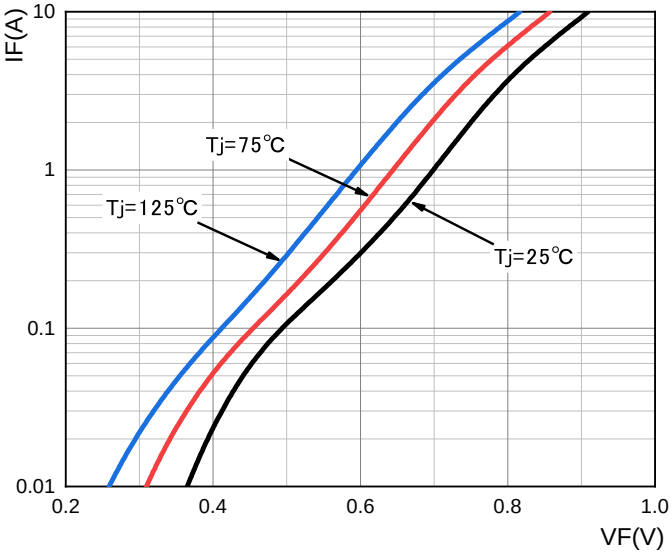
SS515

FIG.10: TYPICAL REVERSE CHARACTERISTICS



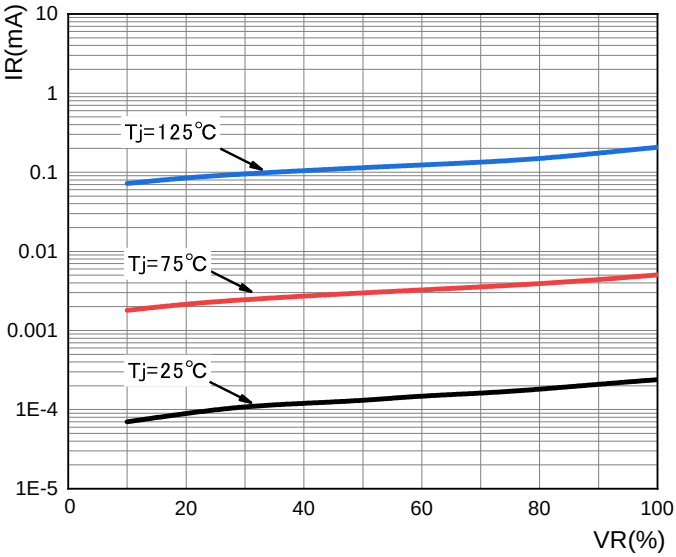
SS520

FIG.11: TYPICAL FORWARD CHARACTERISTICS

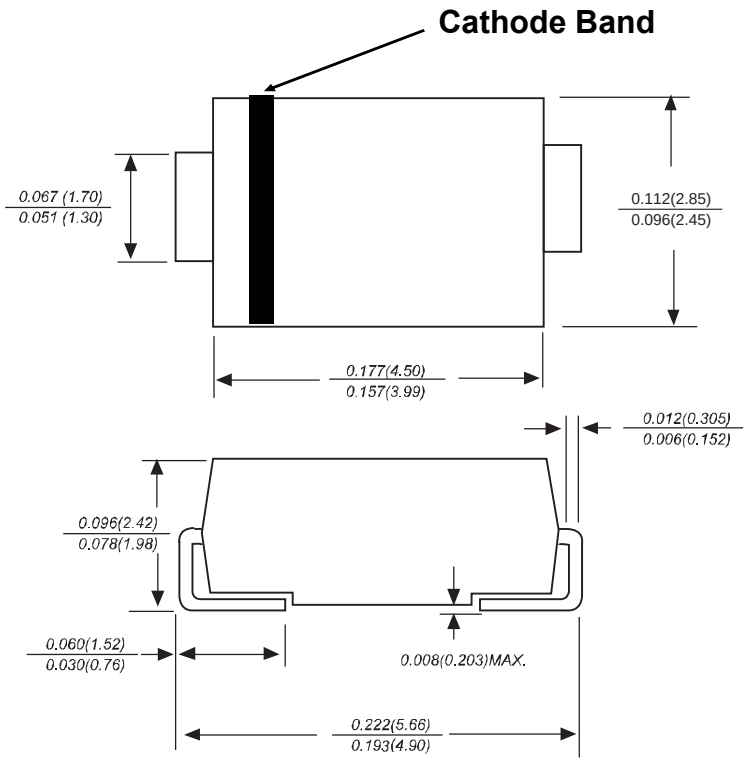


SS520

FIG.12: TYPICAL REVERSE CHARACTERISTICS

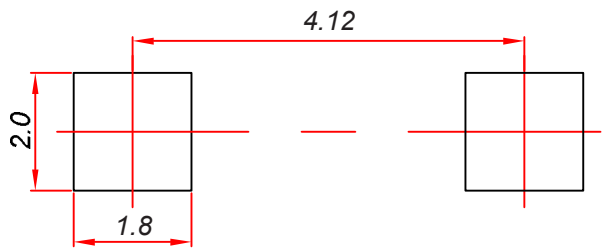


SMAG Package Outline Dimensions



Dimensions in inches and (millimeters)

SMAG Suggested Pad Layout



Note:
1.Controlling dimension:in millimeters.
2.General tolerance:± 0.05mm.
3.The pad layout is for reference purposes only.

NOTICE

SZCJ reserves the right to make modifications,enha nts,improvements,corrections or other es without further notice to any product herein.SZCJ does not assume any liability arising out of the application or use of any product described .

Reel Taping Specifications For Surface Mount Dev ices- SMAG

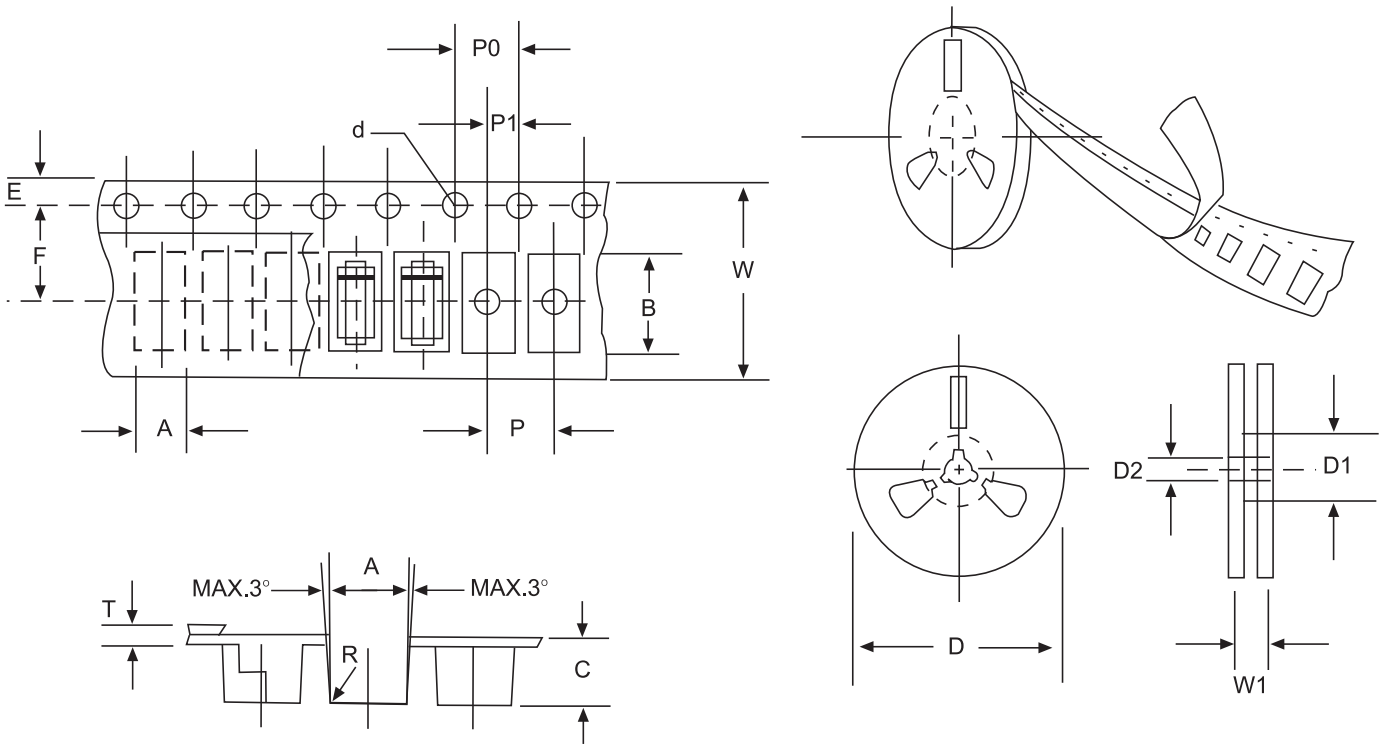


FIG:CONFIGURATION OF SURFACE MOUNTED DEVICES TAPING

ITEM	SYMBOL	SMAG mm(inch)
Carrier width	A	2.79±0.1(0.110±0.004)
Carrier length	B	5.33±0.1(0.210±0.004)
Carrier depth	C	2.36±0.1(0.093±0.004)
Sprocket hole	d	1.55±0.05(0.061±0.002)
Reel outside diameter	D	279±2.0 (11± 0.079)
Reel inner diameter	D1	75 ±1.0 (2.95 ±0.039)
Feed hole diameter	D2	13±0.5(0.512±0.020)
Strocket hole position	E	1.75±0.1(0.069±0.004)
Punch hole position	F	5.5±0.05(0.217±0.002)
Punch hole pitch	P	4.0±0.1(0.157±0.004)
Sprocket hole pitch	P0	4.0±0.1(0.157±0.004)
Embossment center	P1	2.0±0.1(0.079±0.004)
Totall tape thickness	T	0.28±0.02(0.011±0.0008)
Tape width	W	12.0±0.2(0.472±0.008)
Reel width	W1	16.8±2.0(0.661±0.079)

NOTE:Devices are packed in accordance with EIA standard RS-481-A and specification given above.